



RMA258-15R Paste Flux



RMA Paste Flux

Features:

- Excellent Wetting
- Tin-Lead and Lead-Free Compatible
- Used for Ball Attach

Description:

RMA258-15R Paste Flux is a rosin based tacky/rework flux that has been developed to wet virtually all solderable electronic surfaces, components, assemblies, and substrates. RMA258-15R Paste Flux may be used for general touch up or rework of printed circuit boards, and for attaching spheres to ball grid array (BGA) packages. RMA258-15R Paste Flux offers excellent wetting activity whether reflowed by hand, hot-air rework stations, convection reflow ovens, or vapor phase soldering systems. RMA258-15R Paste Flux is compatible with all tin-lead and lead-free alloys and can be used for a wide range of applications. RMA258-15R Paste Flux can be brushed, dispensed, pin transferred, or stencil printed. RMA258-15R Paste Flux is available in 10cc and 30 cc syringes.

The RMA designator is not a current designator of products since QQS-571 and MIL-14256 have been transferred to IPC-J-STD 004, 005 and 006. However, AIM personnel still understand the RMA terminology. Along with the military and federal government specifications that now fall under IPC, the NASA, BS and DIN standards are also still supported by AIM.

Cleaning:

- RMA258-15R Paste Flux is a rosin based formula that may be cleaned if necessary with saponified water or an appropriate solvent cleaner.
- Please refer to the AIM cleaner matrix for a list of compatible cleaning materials.

Handling and Storage:

- RMA258-15R Paste Flux is best used within 1 year at 4° C-12° C (40° F-55° F) or 6 months at room temperature.
- Allow the paste flux to warm up completely and naturally to ambient temperature (2 hrs.) prior to use.
- Mix the product lightly and thoroughly (1-2 mins. max) to ensure even distribution of any separated material.
- Do not store new and used paste flux in the same container.

Safety:

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying Material Safety Data Sheet for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

Physical Properties:

Parameter	Value
J-STD-004	ROL0
Acid Number	133.08 mg +/- 10 % KOH/ g flux

Parameter	Value
Viscosity	Gel-like consistency
Residues	Amber colored

Corrosion Testing:

Parameter	Requirements	Results
Copper Mirror (24 hrs @ 25°C, 50%RH)	IPC-TM-650-2.3.32	Low
Halide Test (Silver Chromate)	IPC-TM-650-2.2.33	Pass

Surface Insulation Resistance:

Requirements	Results
IPC-TM-650 method 2.6.3.7	Pass – See AIM Qualification Test Report

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AIM IS ISO9001:2008 & ISO14001:2004 CERTIFIED

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